



- NOTES:
- PLATING THICKNESS:
ELECTRO Ni: 1.27~8.89 MICRON (SOLDER PADS)
ELECTRO Au: 0.70~1.20 MICRON (SOLDER PADS)
 - CAMBER: 0.05mm MAX.
 - * MARK TO BE MATERIAL DIMENSION.
 - EXPOSURE OF CERAMIC SURFACE OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
 - PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
 - SEALING METHOD OF THIS PRODUCT SHALL BE SEAM WELD.

TOLERANCE	REVISION	SBB ATTACHED EXCEPTIONS SHEET.				TITLE
XX ±1% XXX N.L.T.±0.13 ANGLES	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	7050 X'tal PKG B
	15 : 1	mm	3rd			PART NO. S5070XTAL3
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	REV. 1
90%MIN. Al ₂ O ₃ (NA-301B BLACK)	Shigetomi	Yamahata	Ohba	Ano	Sugi	DWG NO. SHT/OF 1/6
	Jan.23.03	Jan.23.03	Jan.23.03	Jan.23.03	Jan.23.03	